Amendments to the Claims:

Please cancel originally filed claims 1-11.

Please add the following new claims:

12. (new) A printed circuit board, comprising:

a substrate composed of a material initially having a first conductivity;

at least one metal trace formed on said substrate;

wherein said substrate has a plating voltage applied thereto to facilitate a spot-plating operation on said at least one metal trace;

wherein said material responds to a processing step occurring subsequent to said spot-plating operation to cause said material to have a second conductivity, lower than said first conductivity.

13. (new) A printed circuit board in accordance with claim 12, wherein said substrate is composed of an initially partially-cured material and said processing step occurring subsequent to said spot-plating operation comprises a curing operation.

14. (new) A printed circuit board in accordance with claim 12, wherein said first conductivity is in a range between approximately 10^6 and 10^8 ohms per square centimeter.

15. (new) A printed circuit board in accordance with claim 12, wherein said substrate is composed of a carbon-impregnated epoxy.

16. (new) A printed circuit board in accordance with claim 12, wherein said substrate is composed of a polyimid.

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